MECHANICAL

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

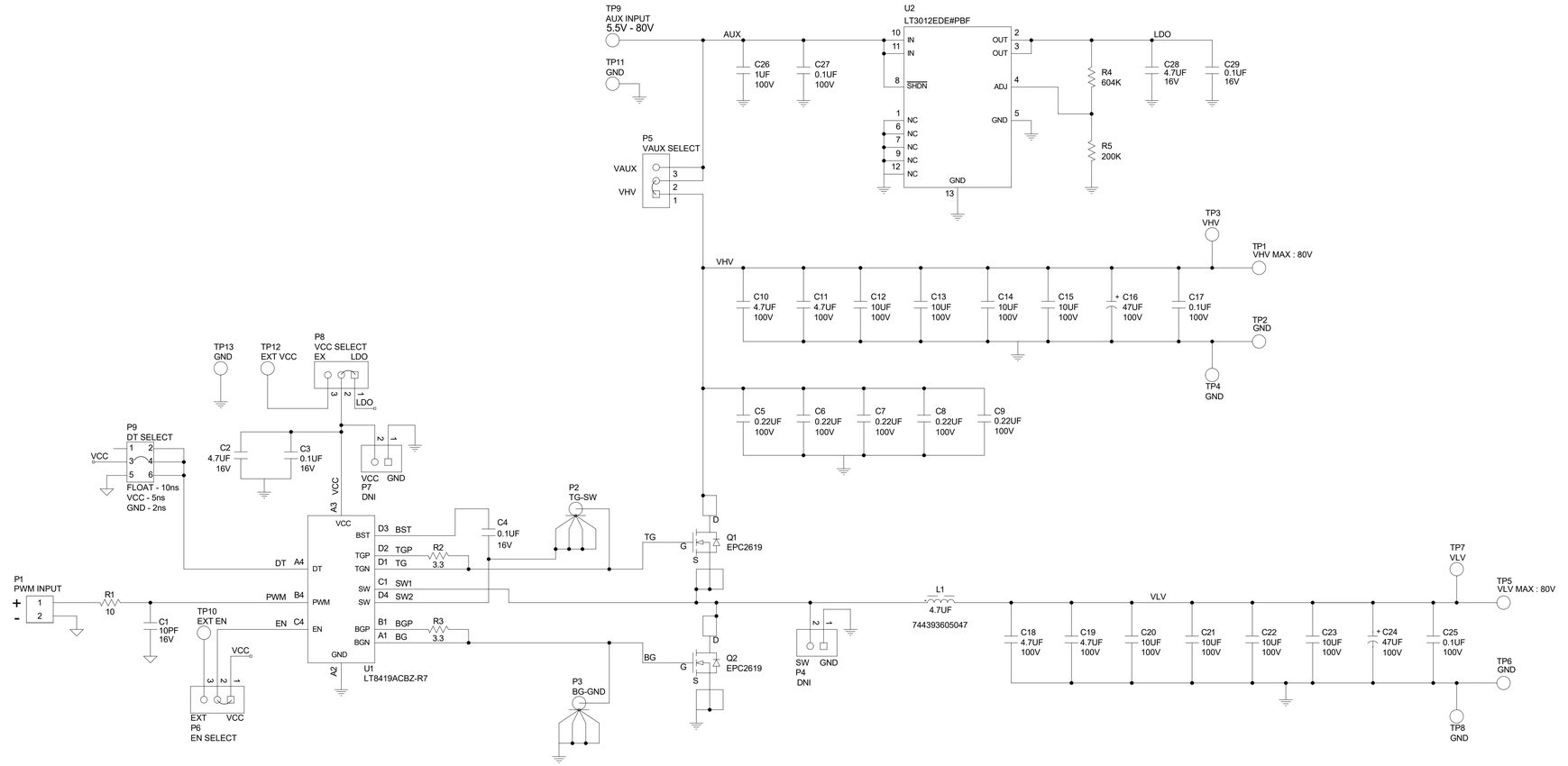
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SCHEMATIC

HW TYPE : Customer Evaluation

Product(s): LT8419

	DATE	DRAWING NO. 02_100210	REV. B
DESIGNER -			
PTD ENGINEER PTD ENGINEER		SIZE C / SCALE 1:1 / TEMPLATE REVISION A	SHEET 1 OF 2



SHORT ON L3 VIA CLOSE TO U1 GND

HEATSINK STANDOFF

P10
P11
P12
P13

To increase thermal dissipation of GaN FETs,
please purchase and install the following heatsink and associated parts on the board:

PART	QUANTITY	PART NUMBER/SIZE
HEATSINK	1	567-45AB
THERMAL PAD	1	TG-A6200-20-20-0.5
SCREW	4	M2x0.4 8mm
WASHER	4	M2

ANALOG DEVICES

SCHEMATIC

HW TYPE : Customer Evaluation
Product(s): LT8419
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DESIGN VIEW: DESIGN_VIEW
DRAWING NO.: 02_100210
REV: B
ENGINEER: PTD ENGINEER
SIZE: D
SCALE: 1:1
SHEET 2 OF 2